



**The Hawaii Wall & Ceiling Industry Association Scholarship Fund
APPLICATIONS MUST BE RECEIVED BY MAY 31, 2025.**

The Hawaii Wall & Ceiling Industry Association Scholarship Fund was established in 2003 to provide educational assistance to members of the HWCIA and/or their dependents who are entering either a two or four-year college.

APPLICATION DEADLINE: Applications must be received by May 31st of each year. Scholarship recipients will be selected in June and funds disbursed in July.

Eligibility Criteria:

- 1) Applicant must be a member, or dependent of a member, of the Hawaii Wall & Ceiling Industry Association as well as a member of the Carpenter's, Taper's, or Plasterer's Unions.
- 2) Member must be in good standing with the association, trust funds and the unions.
- 3) If selected, proof of registration at a qualified educational institute must be presented.
- 4) **Applicant must be enrolled in an accredited college or university as a full time student taking a minimum of 12 credit hours and must maintain a minimum GPA of 2.0.**

Selection Criteria:

- 1) Scholastic Achievement – Most recent transcript must accompany application. A GPA of no less than 2.0 is required.
- 2) Leadership and/or Community Service – Participation in Extracurricular activities in school such as sports, student government and school sponsored organizations. Participation in community service projects.
- 3) A one-page essay describing your future goals.
- 4) Two letters of recommendation – one from a teacher or counselor and another from an employer, minister or community leader who is not related to you.

Instructions:

Completed application form and submit with the required documents and letters by May 31, 2025. If you have any questions, you may call Lisa Kim, Executive Director, at (808) 271-4195.

Email to lisa@hwcia.com or mail to:

HWCIA
3375 Koapaka Street, Suite D131
Honolulu, HI 96819

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Applicant's Full Name: _____ **Date of Birth:** _____

Address: _____ **City,** _____ **State** _____

Zip _____

E-mail: _____ **Phone:** _____

School Presently Attending: _____

Your current Grade Level: _____

Father's Name (or Guardian's Name): _____

Father's Employer: _____ **Union Affiliated with:** _____

Mother's Name (or Guardian's Name): _____

Mother's Employer: _____ **Union Affiliated with:** _____

What field of study do you plan to pursue? _____

What school do you plan on attending? _____

Have you been accepted at this institution? _____

What extracurricular or community activities do you participate in?

Have you received any Awards, Honors or Special Recognition from your school or for community service?
